CMKSH-3T

**SURFACE MOUNT SILICON
TRIPLE ISOLATED
SCHOTTKY DIODE**

SOT-363 CASE

Central™
Semiconductor Corp.

DESCRIPTION:
The CENTRAL SEMICONDUCTOR CMKSH-3T contains three (3) isolated silicon Schottky diodes, epoxy molded in an SOT-363 surface mount package. This device has been designed for switching applications requiring a low forward voltage drop.

MARKING CODE: KHT
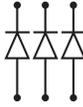
MAXIMUM RATINGS: (T_A=25°C)

	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Continuous Forward Current	I_F	100	mA
Peak Repetitive Forward Current	I_{FRM}	350	mA
Peak Forward Surge Current, tp=10ms	I_{FSM}	750	mA
Power Dissipation	P_D	350	mW
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_R	V_R=25V		90	500	nA
I_R	V_R=25V, T_A=100°C		25	100	μA
BV_R	I_R=100μA	30			V
V_F	I_F=2.0mA		0.29	0.33	V
V_F	I_F=15mA		0.37	0.45	V
V_F	I_F=100mA		0.51	1.00	V
C_J	V_R=1.0V, f=1.0MHz		7.0		pF
t_{rr}	I_F=I_R=10mA, I_{rr}=1.0mA, R_L=100Ω			5.0	ns

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SOT-363 CASE - MECHANICAL OUTLINE

R2
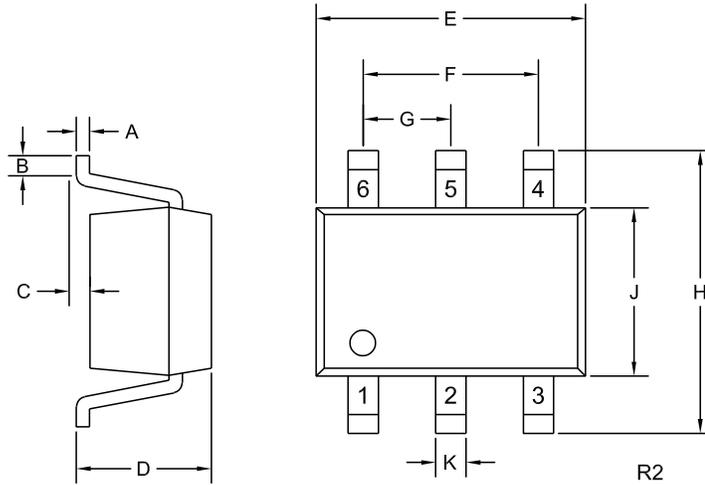
PIN CONFIGURATION
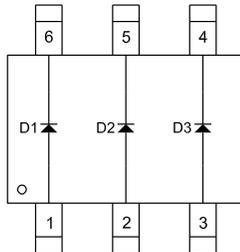
LEAD CODE:
1) Anode D1
2) Anode D2
3) Anode D3
4) Cathode D3
5) Cathode D2
6) Cathode D1

MARKING CODE: KHT

DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.004	0.010	0.10	0.25
B	0.005	-	0.12	-
C	0.000	0.004	0.00	0.10
D	0.031	0.043	0.80	1.10
E	0.071	0.087	1.80	2.20
F	0.051		1.30	
G	0.026		0.65	
H	0.075	0.091	1.90	2.30
J	0.043	0.055	1.10	1.40
K	0.006	0.012	0.15	0.30

SOT-363 (REV: R2)

R5 (11-February 2016)

CMKSH-3T SURFACE MOUNT SILICON TRIPLE ISOLATED SCHOTTKY DIODE	**Central**™ **Semiconductor Corp.**

TYPICAL ELECTRICAL CHARACTERISTICS

Leakage Current

Forward Voltage

Capacitance

Forward Dynamic Impedance

R5 (11-February 2016)

CMKSH-3T

SURFACE MOUNT SILICON
TRIPLE ISOLATED
SCHOTTKY DIODE

Central™
Semiconductor Corp.

TYPICAL ELECTRICAL CHARACTERISTICS

Transient Peak Power and Peak Current Capacity

Current Derating

Power Derating
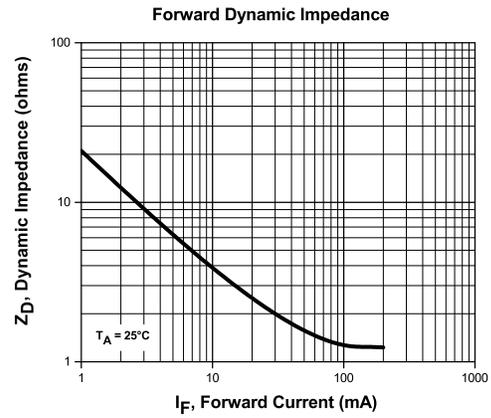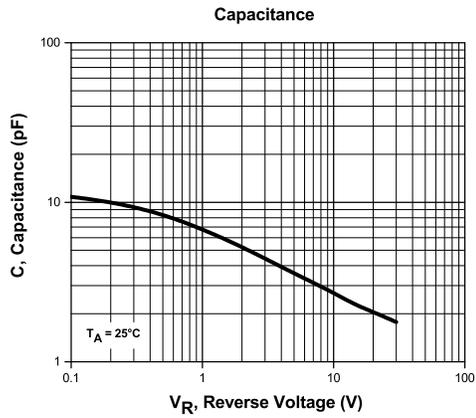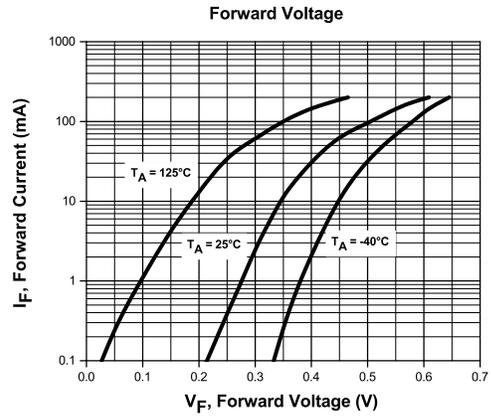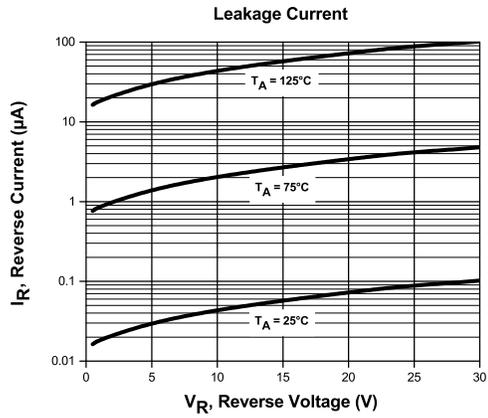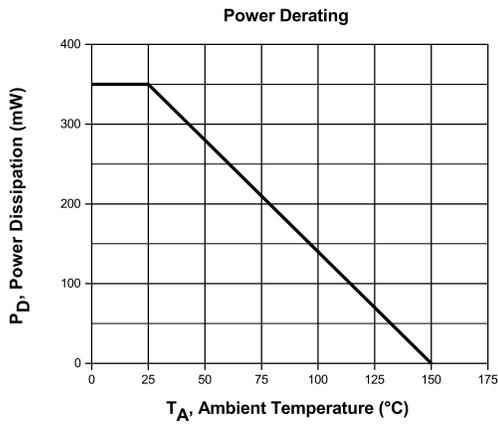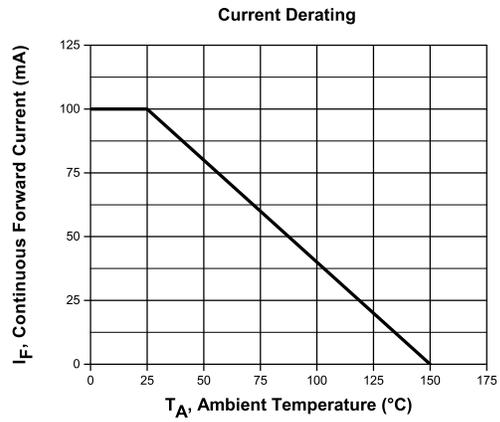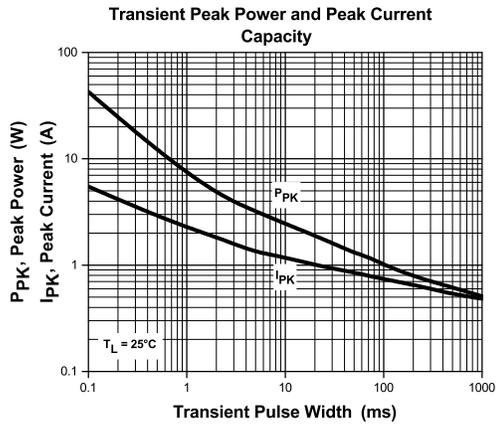
PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

• Supply management (Customer portals)
• Inventory bonding
• Consolidated shipping options

• Custom bar coding for shipments
• Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

• Free quick ship samples (2nd day air)
• Online technical data and parametric search
• SPICE models
• Custom electrical curves
• Environmental regulation compliance
• Customer specific screening
• Up-screening capabilities

• Special wafer diffusions
• PbSn plating options
• Package details
• Application notes
• Application and design sample kits
• Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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